1-1734261-4 SUPERSEDED

TE Internal #: 1-1734261-4

TE Internal Description: 1.25 WTB, HDR, SMT, RA, 14P

AMP HPI 1.25 mm Headers

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Connector System: Wire-to-Board

Number of Positions: 14

Number of Rows: 1

Centerline (Pitch): 1.25 mm [.049 in]
PCB Mount Orientation: Right Angle

All AMP HPI 1.25 mm Headers (0)

Features

Product Type Features

| Connector System | Wire-to-Board |
|-----------------------------------|-----------------------|
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| Number of Positions | 14 |
| Number of Rows | 1 |
| PCB Mount Orientation | Right Angle |

Electrical Characteristics

| Operating Voltage | 100 VAC | |
|-------------------|---------|--|
| Operating voltage | 100 VAC | |

Body Features



| Primary Product Color | Natural |
|---|--------------------------------|
| Contact Features | |
| PCB Contact Termination Area Plating Material Thickness | 2.54 μm[100 μin] |
| Contact Layout | Inline |
| Mating Tab Width | .74 mm[.029 in] |
| Mating Tab Thickness | .3 mm[.012 in] |
| Contact Mating Area Plating Material Thickness | 2.54 μm[100 μin] |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Mating Area Plating Material Finish | Matte |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Nickel |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .3 mm[.012 in] |
| Terminations per Post (Max) | 3 |
| Rectangular Termination Post & Tail Width | .35 mm[.014 in] |
| Termination Method to PCB | Surface Mount |
| Mechanical Attachment | |
| Mating Alignment Type | Polarization |
| Mating Retention | Without |
| PCB Mount Retention Type | Solder Peg |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | With |
| Housing Features | |
| Housing Material | High Temperature Thermoplastic |
| Centerline (Pitch) | 1.25 mm[.049 in] |
| Dimensions | |
| Connector Length | 22.79 mm[.897 in] |
| | |



| Connector Height | 3.45 mm[.136 in] |
|-----------------------------|---------------------------|
| Connector Width | 4.7 mm[.185 in] |
| Usage Conditions | |
| Operating Temperature Range | -25 – 85 °C[-13 – 185 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 1000 |
| Packaging Method | Reel |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Not Yet Reviewed |
|---|---|
| EU ELV Directive 2000/53/EC | Not Yet Reviewed |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUN 2015 (163) SVHC > Threshold: Not Yet Reviewed |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Customers Also Bought













Documents

Product Drawings

1.25 WTB, HDR, SMT, RA, 14P

English

CAD Files

Customer View Model

ENG_CVM_1-1734261-4_A.3d_igs.zip

English

Customer View Model

ENG_CVM_1-1734261-4_A.3d_stp.zip

English

Customer View Model

ENG_CVM_1-1734261-4_A.2d_dxf.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

HPI Connectors QRG

English

Product Specifications

Product Specification

English

